

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L7	0	(29/611,840,846).ccls. and ((coupl\$3 or attach\$3 or connect\$3) near (component or chip or IC)) with (snap\$4) and (fus\$ or solder\$3 or melt\$3) and (size)	US-PGPUB; USPAT; IBM_TDB	OR	ON	2006/04/12 18:23
L8	5	(29/611,840,846).ccls. and ((coupl\$3 or attach\$3 or connect\$3) with (component or chip or IC)) with (snap\$4) and (fus\$ or solder\$3 or melt\$3) and (size)	US-PGPUB; USPAT; IBM_TDB	OR	ON	2006/04/12 18:16
L9	3	(439/65,329).ccls. and ((coupl\$3 or attach\$3 or connect\$3) with (component or chip or IC)) with (snap\$4) and (fus\$ or solder\$3 or melt\$3) and (size)	US-PGPUB; USPAT; IBM_TDB	OR	ON	2006/04/12 18:17
L10	3	(361/803).ccls. and ((coupl\$3 or attach\$3 or connect\$3) with (component or chip or IC)) with (snap\$4) and (fus\$ or solder\$3 or melt\$3) and (size)	US-PGPUB; USPAT; IBM_TDB	OR	ON	2006/04/12 18:17
L11	8	(257/678).ccls. and ((coupl\$3 or attach\$3 or connect\$3) with (component or chip or IC)) with (snap\$4) and (fus\$ or solder\$3 or melt\$3) and (size)	US-PGPUB; USPAT; IBM_TDB	OR	ON	2006/04/12 18:18
L12	0	(977/724).ccls. and ((coupl\$3 or attach\$3 or connect\$3) near (component or chip or IC)) with (snap\$4) and (fus\$ or solder\$3 or melt\$3) and (size)	US-PGPUB; USPAT; IBM_TDB	OR	ON	2006/04/12 18:19
L15	17	("977"/\$).ccls. and ((coupl\$3 or attach\$3 or connect\$3) near (component or chip or IC)) and (fus\$ or solder\$3 or melt\$3) and (size with nano\$)	US-PGPUB; USPAT; IBM_TDB	OR	ON	2006/04/12 18:21
L20	4	((coupl\$3 or attach\$3 or connect\$3 or position\$3) with (microcomponent)) with (contact or snap\$4) and (fus\$ or solder\$3 or melt\$3 or heat\$3 or activat\$3) and (size)	US-PGPUB	OR	ON	2006/04/12 18:26
S1	2	(nilsen-erik).in.	US-PGPUB; USPAT; IBM_TDB	OR	ON	2005/11/03 07:19
S2	12	(ellis-matthew-d).in.	US-PGPUB; USPAT; IBM_TDB	OR	ON	2005/11/02 13:28

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S3	13	(goldsmith-charles-l).in.	US-PGPUB; USPAT; IBM_TDB	OR	ON	2005/11/02 13:28
S4	1	(huang-xiaojun).in.	US-PGPUB; USPAT; IBM_TDB	OR	ON	2005/11/03 07:20
S5	0	(nallani-arun-kumar).in.	US-PGPUB; USPAT; IBM_TDB	OR	ON	2005/11/03 07:20
S6	0	(kumar-nallani-arun).in.	US-PGPUB; USPAT; IBM_TDB	OR	ON	2005/11/03 07:21
S7	0	(arun-kumar-nallani).in.	US-PGPUB; USPAT; IBM_TDB	OR	ON	2005/11/03 07:21
S8	2	(kim-kabseog).in.	US-PGPUB; USPAT; IBM_TDB	OR	ON	2006/02/01 08:35
S9	11	(skidmore-george-d).in.	US-PGPUB; USPAT; IBM_TDB	OR	ON	2005/11/13 06:22
S10	0	"29"/\$.ccls. and (microcomponent adj interconnection)	US-PGPUB; USPAT; IBM_TDB	OR	ON	2005/11/13 06:26
S11	0	(microcomponent adj interconnection)	US-PGPUB; USPAT; IBM_TDB	OR	ON	2005/11/13 06:23
S12	2	(microcomponent near interconnection)	US-PGPUB; USPAT; IBM_TDB	OR	ON	2006/04/11 13:02
S13	1	"29"/\$.ccls. and (microcomponent adj connection)	US-PGPUB; USPAT; IBM_TDB	OR	ON	2005/11/13 06:26
S14	3	"29"/\$.ccls. and interconnection with component with parallel with contact	US-PGPUB; USPAT; IBM_TDB	OR	ON	2006/02/01 08:35

EAST Search History

S15	30	US-3268774-\$.DID. OR US-3439416-\$.DID. OR US-3467942-\$.DID. OR US-3588618-\$.DID. OR US-4018409-\$.DID. OR US-4141138-\$.DID. OR US-4383195-\$.DID. OR US-4740410-\$.DID. OR US-4852242-\$.DID. OR US-4911098-\$.DID. OR US-4955814-\$.DID. OR US-4963748-\$.DID. OR US-4969827-\$.DID. OR US-5025346-\$.DID. OR US-5072288-\$.DID. OR US-5092781-\$.DID. OR US-5113117-\$.DID. OR US-5122663-\$.DID. OR US-5160877-\$.DID. OR US-5215923-\$.DID. OR US-5273441-\$.DID. OR US-5399415-\$.DID. OR US-5411400-\$.DID. OR US-5538305-\$.DID. OR US-5539200-\$.DID. OR US-5610335-\$.DID. OR US-5645684-\$.DID. OR US-5657516-\$.DID. OR US-5660680-\$.DID. OR US-5746621-\$.DID.	US-PGPUB; USPAT; IBM_TDB	OR	ON	2006/04/11 13:03
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EAST Search History

S16	75	((("3268774") or ("3439416") or ("3467942") or ("3588618") or ("4018409") or ("4141138") or ("4383195") or ("4740410") or ("4852242") or ("4911098") or ("4955814") or ("4963748") or ("4969827") or ("5025346") or ("5072288") or ("5092781") or ("5113117") or ("5122663") or ("5160877") or ("5215923") or ("5273441") or ("5399415") or ("5411400") or ("5538305") or ("5539200") or ("5610335") or ("5645684") or ("5657516") or ("5660680") or ("5746621") or ("5774956") or ("5806152") or ("5818748") or ("5848456") or ("5867302") or ("5895084") or ("5963788") or ("6103399") or ("6154936") or ("6193541") or ("6215081") or ("6218664") or ("6219254") or ("6239685") or ("6257925") or ("6263549") or ("20010010348") or ("6300156") or ("6303885") or ("6321654") or ("6396711") or ("6398280") or ("6398280") or ("20020125208") or ("6483419") or ("6488315") or ("6531947") or ("6561725") or ("6175522") or ("20030201654") or ("20030210115") or ("6672795") or ("6678458") or ("6679055") or ("6691513") or ("6745567") or ("6762116") or ("6764325") or ("20040135526") or ("6837723") or ("6862921") or ("6881074") or ("6923669") or ("6,131,277") or ("6,193,139") or ("6,429,113")).PN.	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2006/04/11 13:43
S17	38289	coupl\$3 with (microcomponent or connect\$3) same (activat\$3 or cur\$3 or heat\$3)	US-PGPUB; USPAT; IBM_TDB	OR	ON	2006/04/11 13:45
S18	1985	(coupl\$3 near (microcomponent or connect\$3)) with (activat\$3 or cur\$3 or heat\$3)	US-PGPUB; USPAT; IBM_TDB	OR	ON	2006/04/11 13:46
S19	76	(coupl\$3 near (microcomponent or connect\$3)) with (activat\$3 or cur\$3 or heat\$3) same (fus\$ or solder\$3 or melt\$3)	US-PGPUB; USPAT; IBM_TDB	OR	ON	2006/04/11 13:47
S20	10	("20020125208" "5963788" "6103399" "6219254" "6300156" "6398280" "6561725" "6672795" "6745567" "6762116").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/04/11 14:05

EAST Search History

S21	8	("4740410" "5602955" "5645684" "5660680" "5692086" "5745624" "5962949" "6164837").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/04/11 14:07
S22	21	("3268774" "3439416" "3467942" "4141138" "4740410" "4955814" "4969827" "5113117" "5411400" "5539200" "5645684" "5657516" "5660680" "5806152" "5818748" "5848456" "6154936" "6263549").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/04/11 14:09
S23	8	("4740410" "5602955" "5645684" "5660680" "5692086" "5745624" "5962949" "6164837").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/04/12 10:27
S24	21	("3268774" "3439416" "3467942" "4141138" "4740410" "4955814" "4969827" "5113117" "5411400" "5539200" "5645684" "5657516" "5660680" "5806152" "5818748" "5848456" "6154936" "6263549").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/04/12 10:49
S25	14	("4955814").URPN.	USPAT	OR	ON	2006/04/12 10:52

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S26	79	("20010010348" "20020125208" "20030201654" "20030210115" "20040135526" "3268774" "3439416" "3467942" "3588618" "4018409" "4141138" "4383195" "4740410" "4852242" "4911098" "4955814" "4963748" "4969827" "5025346" "5072288" "5092781" "5113117" "5122663" "5160877" "5215923" "5273441" "5399415" "5411400" "5538305" "5539200" "5610335" "5645684" "5657516" "5660680" "5746621" "5774956" "5806152" "5818748" "5848456" "5867302" "5895084" "5963788" "6103399" "6131277" "6154936" "6193139" "6193541" "6215081" "6218664" "6219254" "6239685" "6257925" "6263549" "6300156" "6303885" "6321654" "6396711" "6398280" "6429113" "6483419" "6488315" "6531947" "6561725" "6617522" "6672795" "6678458" "6679055" "6691513" "6745567" "6762116" "6764325" "6837723" "6862921" "6881074" "6923669").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/04/12 10:53
S27	12	((coupl\$3 near (microcomponent or connect\$3)) with (activat\$3 or cur\$3 or heat\$3) same (fus\$ or solder\$3 or melt\$3)) and snap\$4	US-PGPUB; USPAT; IBM_TDB	OR	ON	2006/04/12 11:14
S28	7	("5027845").URPN.	USPAT	OR	ON	2006/04/12 11:12
S29	70	((coupl\$3 with (microcomponent or connect\$3)) with (activat\$3 or cur\$3 or heat\$3) same (fus\$ or solder\$3 or melt\$3)) and snap\$4	US-PGPUB; USPAT; IBM_TDB	OR	ON	2006/04/12 11:15
S30	0	((coupl\$3 or attach\$3 or connect\$3) with microcomponent with (activat\$3 or cur\$3 or heat\$3) same (fus\$ or solder\$3 or melt\$3)) and snap\$4	US-PGPUB; USPAT; IBM_TDB	OR	ON	2006/04/12 11:16
S31	1	((coupl\$3 or attach\$3 or connect\$3) with microcomponent with (activat\$3 or cur\$3 or heat\$3)) same (fus\$ or solder\$3 or melt\$3)	US-PGPUB; USPAT; IBM_TDB	OR	ON	2006/04/12 11:17

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S32	3049	((coupl\$3 or attach\$3 or connect\$3) with (activat\$3 or cur\$3 or heat\$3)) same (fus\$ or solder\$3 or melt\$3) and snap\$4	US-PGPUB; USPAT; IBM_TDB	OR	ON	2006/04/12 11:18
S33	20687	((coupl\$3 or attach\$3 or connect\$3) with (activat\$3 or cur\$3 or heat\$3)) with (fus\$ or solder\$3 or melt\$3) same (snap\$4 or plug\$4 or connect\$3)	US-PGPUB; USPAT; IBM_TDB	OR	ON	2006/04/12 11:18
S34	843	((coupl\$3 or attach\$3 or connect\$3) with (activat\$3 or cur\$3 or heat\$3)) with (fus\$ or solder\$3 or melt\$3) same (snap\$4 or plug\$4)	US-PGPUB; USPAT; IBM_TDB	OR	ON	2006/04/12 11:19
S35	465	(coupl\$3 or attach\$3 or connect\$3) with (activat\$3 or cur\$3 or heat\$3) with (fus\$ or solder\$3 or melt\$3) with (snap\$4 or plug\$4)	US-PGPUB; USPAT; IBM_TDB	OR	ON	2006/04/12 11:20
S36	87	(coupl\$3 or attach\$3 or connect\$3) with ((activat\$3 or cur\$3 or heat\$3) near (fus\$ or solder\$3 or melt\$3)) with (snap\$4 or plug\$4)	US-PGPUB; USPAT; IBM_TDB	OR	ON	2006/04/12 11:36
S37	220	(coupl\$3 or attach\$3 or connect\$3) with (fusible) with (snap\$4 or plug\$4)	US-PGPUB; USPAT; IBM_TDB	OR	ON	2006/04/12 11:39
S38	1	(coupl\$3 or attach\$3 or connect\$3) with (fusible adj solder) with (snap\$4 or plug\$4)	US-PGPUB; USPAT; IBM_TDB	OR	ON	2006/04/12 11:37
S39	0	(coupl\$3 or attach\$3 or connect\$3) with (fusible) with (snap\$4 or plug\$4) and microcomponent	US-PGPUB; USPAT; IBM_TDB	OR	ON	2006/04/12 11:38
S40	18818	(liquid adj crystal adj display) and area and head	US-PGPUB; USPAT; IBM_TDB	OR	ON	2006/04/12 12:11
S41	1598	(liquid adj crystal adj display) with area and head	US-PGPUB; USPAT; IBM_TDB	OR	ON	2006/04/12 12:11
S42	94	(liquid adj crystal adj display) with area and head with heat	US-PGPUB; USPAT; IBM_TDB	OR	ON	2006/04/12 12:14
S43	0	(liquid adj crystal adj display) with area and (head with heat) and bpard	US-PGPUB; USPAT; IBM_TDB	OR	ON	2006/04/12 12:12
S44	8	(liquid adj crystal adj display) with area and (head with heat) and board	US-PGPUB; USPAT; IBM_TDB	OR	ON	2006/04/12 12:12
S45	126	((liquid adj crystal adj display) or LCD) with area and head with heat	US-PGPUB; USPAT; IBM_TDB	OR	ON	2006/04/12 12:14

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S46	0	((liquid adj crystal adj display) or LCD) with area and header with heat	US-PGPUB; USPAT; IBM_TDB	OR	ON	2006/04/12 12:14
S47	0	((liquid adj crystal adj display) or LCD) same area and header with heat	US-PGPUB; USPAT; IBM_TDB	OR	ON	2006/04/12 12:14
S48	0	((liquid adj crystal adj display) or LCD) same area and header with heat	US-PGPUB; USPAT; IBM_TDB	OR	ON	2006/04/12 12:15
S49	8	((liquid adj crystal adj display) or LCD) same area and header same heat	US-PGPUB; USPAT; IBM_TDB	OR	ON	2006/04/12 12:15
S50	9	((liquid adj crystal adj display) or LCD) same area and header same heat\$3	US-PGPUB; USPAT; IBM_TDB	OR	ON	2006/04/12 12:15
S51	24988	((coupl\$3 or attach\$3 or connect\$3) with (microcomponent or component or chip or IC) with (fus\$ or solder\$3 or melt\$3)) same (snap\$4 or plug\$4 or connect\$3)	US-PGPUB; USPAT; IBM_TDB	OR	ON	2006/04/12 12:33
S52	223	((coupl\$3 or attach\$3 or connect\$3) with (microcomponent or component or chip or IC) with (fus\$ or solder\$3 or melt\$3)) same (snap\$4)	US-PGPUB; USPAT; IBM_TDB	OR	ON	2006/04/12 12:34
S53	75	((coupl\$3 or attach\$3 or connect\$3) with (microcomponent or component or chip or IC) with (fus\$ or solder\$3 or melt\$3)) with (snap\$4)	US-PGPUB; USPAT; IBM_TDB	OR	ON	2006/04/12 13:03
S54	5	(coupl\$3 or attach\$3 or connect\$3) with ((two or many or together or "each other") near (microcomponent or component or chip or IC)) with (fus\$ or solder\$3 or melt\$3) with (snap\$4)	US-PGPUB; USPAT; IBM_TDB	OR	ON	2006/04/12 13:11
S55	1	(coupl\$3 or attach\$3 or connect\$3) with ((two or many or together or "each other") near (board or device)) with (fus\$ or solder\$3 or melt\$3) with (snap\$4)	US-PGPUB; USPAT; IBM_TDB	OR	ON	2006/04/12 13:09
S56	59	(coupl\$3 or attach\$3 or connect\$3) with ((two or many or together or "each other") near (microcomponent or component or chip or IC or board or device)) with (snap\$4) and (fus\$ or solder\$3 or melt\$3)	US-PGPUB; USPAT; IBM_TDB	OR	ON	2006/04/12 15:13

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S57	12	("3439416" "4141138" "4740410" "5113117" "5645684" "5657516" "5660680" "5806152" "5818748" "6193541" "6257925").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/04/12 13:43
S58	21	("3268774" "3439416" "3467942" "4141138" "4740410" "4955814" "4969827" "5113117" "5411400" "5539200" "5645684" "5657516" "5660680" "5806152" "5818748" "5848456" "6154936" "6263549").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/04/12 14:03
S59	15	("5411400").URPN.	USPAT	OR	ON	2006/04/12 14:15
S60	8	("4703559" "5127838" "5364277" "5411400" "5509840" "5545367" "5576147" "5818748").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/04/12 14:31
S61	11	("5724728").URPN.	USPAT	OR	ON	2006/04/12 14:52
S62	545	(coupl\$3 or attach\$3 or connect\$3) with (microcomponent or component or chip or IC) with (snap\$4) and (fus\$ or solder\$3 or melt\$3) and size	US-PGPUB; USPAT; IBM_TDB	OR	ON	2006/04/12 15:39
S63	29	(coupl\$3 or attach\$3 or connect\$3) with (microcomponent or component or chip or IC) with (snap\$4) and (fus\$ or solder\$3 or melt\$3) and (size with micro\$3)	US-PGPUB; USPAT; IBM_TDB	OR	ON	2006/04/12 15:37
S64	11	("5724728").URPN.	USPAT	OR	ON	2006/04/12 15:29
S65	372	(coupl\$3 or attach\$3 or connect\$3) with (snap\$4) and (fus\$ or solder\$3 or melt\$3) and (size with micro\$3)	US-PGPUB; USPAT; IBM_TDB	OR	ON	2006/04/12 15:38
S66	316	(coupl\$3 or attach\$3 or connect\$3) with (snap\$4) and (fus\$ or solder\$3 or melt\$3) and (size with micron)	US-PGPUB; USPAT; IBM_TDB	OR	ON	2006/04/12 15:38
S67	0	(coupl\$3 or attach\$3 or connect\$3) near (micro adj (component or chip or IC)) with (snap\$4) and (fus\$ or solder\$3 or melt\$3) and size	US-PGPUB; USPAT; IBM_TDB	OR	ON	2006/04/12 15:40
S68	13	((coupl\$3 or attach\$3 or connect\$3) near (component or chip or IC)) with (snap\$4) and (fus\$ or solder\$3 or melt\$3) and (size with micron)	US-PGPUB; USPAT; IBM_TDB	OR	ON	2006/04/12 16:00
S69	44	((coupl\$3 or attach\$3 or connect\$3) near (component or chip or IC)) with (snap\$4) and (fus\$ or solder\$3 or melt\$3) and (micron)	US-PGPUB; USPAT; IBM_TDB	OR	ON	2006/04/12 15:42

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S70	22	((coupl\$3 or attach\$3 or connect\$3) near (component or chip or IC)) with (snap\$4) and (fus\$ or solder\$3 or melt\$3) and (size with nano\$)	US-PGPUB; USPAT; IBM_TDB	OR	ON	2006/04/12 18:14
S71	0	((mount\$3 or install\$3) near (component or chip or IC)) with (snap\$4) and (fus\$ or solder\$3 or melt\$3) and (size with nano\$)	US-PGPUB; USPAT; IBM_TDB	OR	ON	2006/04/12 16:03
S72	1	((mount\$3 or install\$3) near (component or chip or IC)) with (snap\$4) and (fus\$ or solder\$3 or melt\$3) and (size with (micron or nano\$))	US-PGPUB; USPAT; IBM_TDB	OR	ON	2006/04/12 16:04